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TRANSMITTAL FORM

I hereby certify that this correspondence is being deposited with the United States Postal Service as "Express Mail" under Label No. EV 275480558 US in an envelope addressed to: Mail Stop: Patent Application, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on:

Feb. 26/04
(Date of Deposit)

Mail Stop: Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Attorney Doc. #: 67,200-1122
Mailing Date: Feb. 26, 2004

Dear Sir:

Transmitted herewith for filing is the patent application of:

Inventor(s):

KAI TZENG
CHU-WEI HU
KUEI-YUAM HSU

CHEN-MING WU
JUNG-LIEH HSU

For: A METHOD TO PREVENT PASSIVATION LAYER PEELING IN A
SOLDER BUMP FORMATION PROCESS

Submitted herewith are:

2 sheet(s) of formal drawings

An Assignment of the invention to Taiwan Semiconductor Manufacturing Co., Ltd., together with
Assignment Recordal Sheet

A Declaration for patent application under CFR 1.63 and 1.68

The filing fee has been calculated as shown below:

	No. Filed	No. Extra	Small Entity Fee	Large Entity Fee	Total
Basic Fee			\$385.00	\$770.00	\$770.00
Total Claims	20 X 20		\$9.00	\$18.00	\$0
Indep. Claims	2 -3		\$43.00	\$86.00	\$0
Multiple Dep. Clms.			\$145.00	\$290.00	\$0
Assign. Rec. Fee			\$40.00	\$40.00	\$40.00
TOTAL					\$810.00

Mailing Date: Feb. 26, 2004

Attorney Docket No.: 67200-1122

Attached is a Credit Card Payment Form for the sum of \$ 810.00
A duplicate copy of this transmittal is attached.

The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Visa Credit Card No. 4756 8461 9568 0263.

- Any additional filing fees required under 37 CFR 1.6
 Any patent application processing fees under 37 CFR 1.17

Respectfully submitted,

TUNG & ASSOCIATES

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